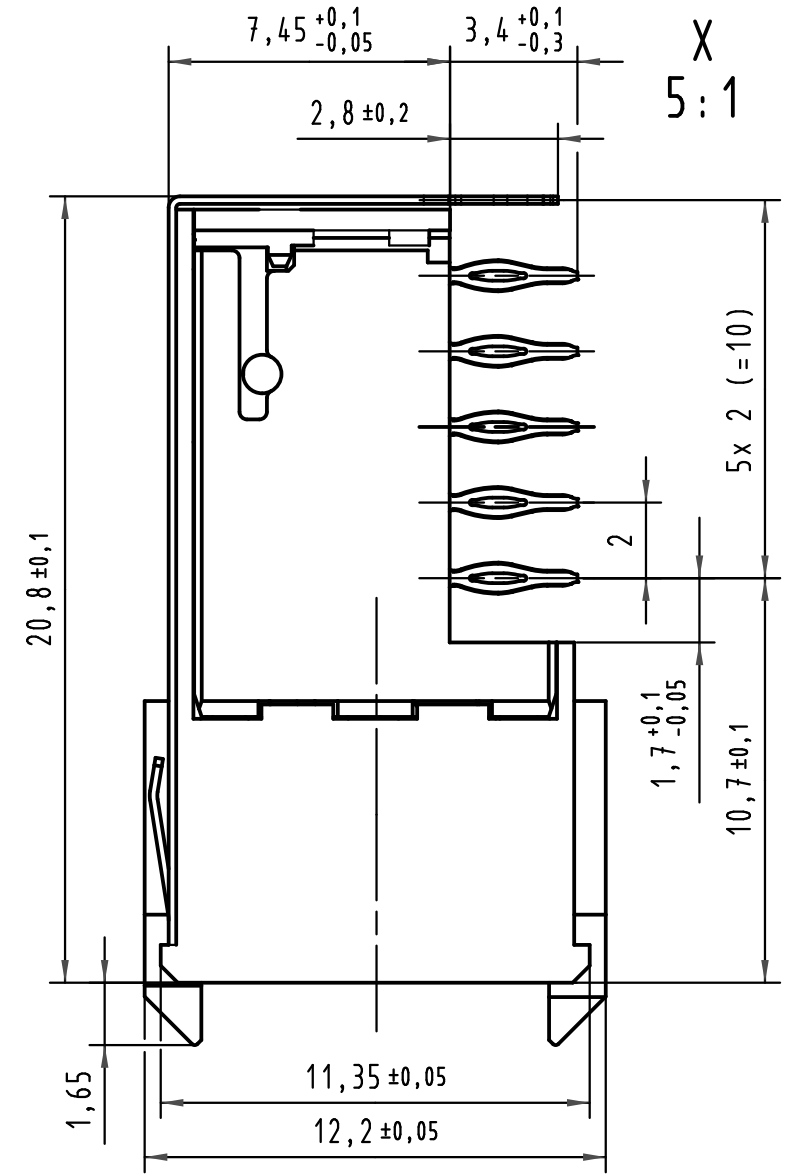
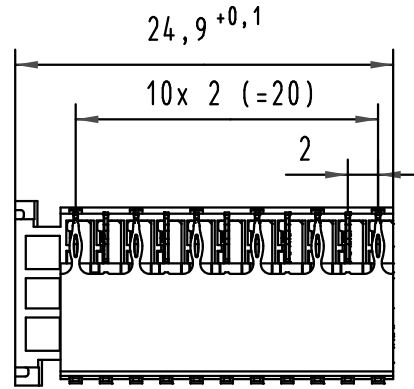
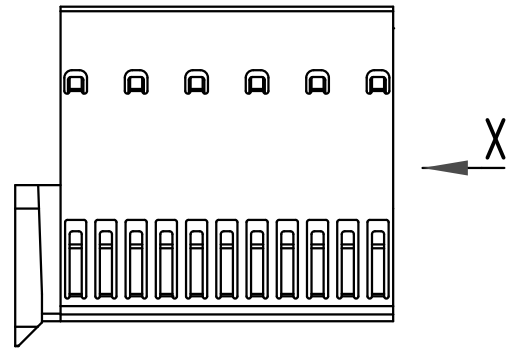
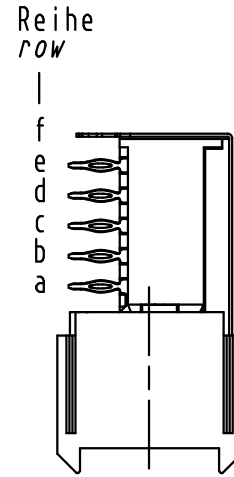
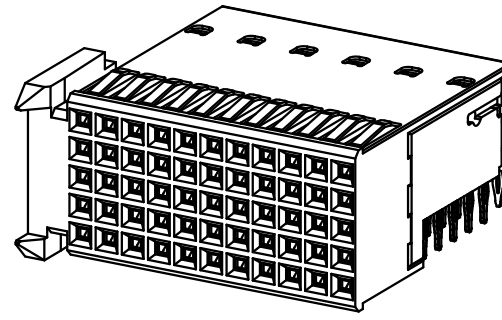
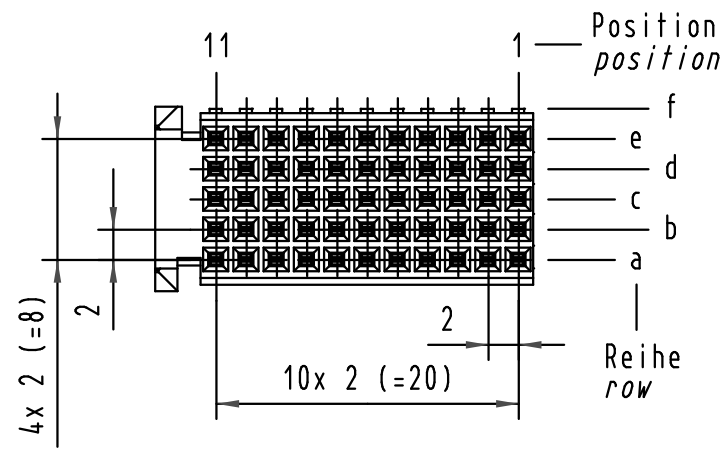
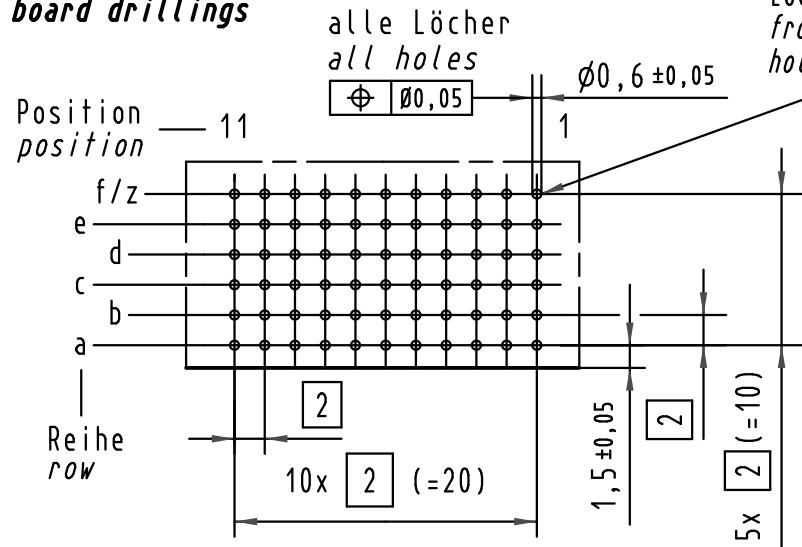


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**Lochbild
board drillings**



Von f/z/1 aus, jedes 2.
Loch f. obere Abschirmung
from f/z/1, each 2nd
hole f. upper shielding

Bohrlochdurchmesser: $\phi 0,7 \pm 0,02$ mm
Lochdurchmesser (mit Oberfläche): $\phi 0,6 \pm 0,05$ mm
drill hole dia.: $\phi 0,7 \pm 0,02$ mm
through hole dia. (after plating): $\phi 0,6 \pm 0,05$ mm

17 23 055 4102	—	min.0,76 μ m (30 μ m) Au über/over min.1,27 μ m (50 μ m) Ni
17 23 055 2102	2	Au über/over Ni
17 23 055 1102	1	Au über/over Ni
Bestell-Nr. part-no.	Anforderungsstufe nach IEC performance level acc. to IEC	Kontaktoberfläche contact plating

All Dimensions in mm Original Size DIN A 3			Techn. Character.			Nicht tolerierte Maß/Free size tolerances IEC 61076-4-101		
				Dat.	Name	Maßstab/Scale 2:1 (5:1)	har-bus HM Federleiste, Typ C, 55 pol. mit Schirmblech Reihe-f har-bus HM female connector, type C, 55 pol. with shield row-f	
35456	01.12.08	TD	Detail.	29.06.99	Hm			
32387	18.11.04	HL.	Insp.	29.06.99	Ko			
29412	07.05.01	Lk	Stand.					
28494	20.09.00	Koe	HARTING Electronics GmbH & Co. KG				TB 17 23 055 x102	
25016			D-32339 ESPELKAMP					
Mod.	Dat.	Name					Sub.	Blatt/ page